

# UNISONIC TECHNOLOGIES CO., LTD

# UT4421

Preliminary

# -6.2A, -60V P-CHANNEL **POWER MOSFET**

#### DESCRIPTION

The UTC UT4421 is a P-channel MOSFET, it uses UTC's advanced technology to provide the customers with a minimum on state resistance and high switching speed.

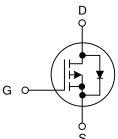
The UTC UT4421 is suitable for load switch and battery protection applications.

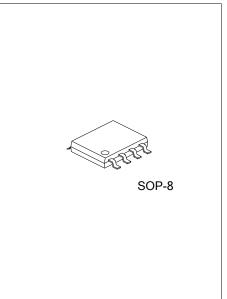
#### **FEATURES**

\*  $R_{DS(ON)}$  < 40m $\Omega$  @  $V_{GS}$ = -10V,  $I_D$ = -6.2A

- $R_{DS(ON)} < 50m\Omega @ V_{GS} = -4.5V, I_D = -5A$
- \* High switching speed

#### **SYMBOL**



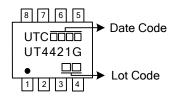


#### **ORDERING INFORMATION**

Ordering Number	Daakaga	Pin Assignment								Decking	
Ordering Number	Package	1	2	3	4	5	6	7	8	Packing	
UT4421G-S08-R	UT4421G-S08-R SOP-8		S	S	G	D	D	D	D	Tape Reel	
Note: Pin Assignment: G: Gate D: Drain	ote: Pin Assignment: G: Gate D: Drain S: Source										
UT4421 <u>G-S08-R</u>		-	_								

(1)Packing Type	(1) R: Tape Reel
(2)Package Type	(2) S08: SOP-8
(3)Green Package	(3) G: Halogen Free and Lead Free

#### MARKING



### ■ **ABSOLUTE MAXIMUM RATINGS** (T<sub>A</sub>=25°C unless otherwise noted)

PARAMETER		SYMBOL	RATINGS	UNIT
Drain-Source Voltage		V <sub>DSS</sub>	-60	V
Gate-Source Voltage		V <sub>GSS</sub>	±20	V
Drain Current	Continuous T <sub>A</sub> =25°C		-6.2	А
	(Note 1) T <sub>A</sub> =70°C	ID	-5	А
	Pulsed (Note 2)	I <sub>DM</sub>	-40	А
Power Dissipation (N	lote 1)	PD	2	W
Junction Temperature		TJ	-55~+150	°C
Storage Temperature Range		T <sub>STG</sub>	-55~+150	°C

Note: Absolute maximum ratings are those values beyond which the device could be permanently damaged. Absolute maximum ratings are stress ratings only and functional device operation is not implied.

## THERMAL DATA

H	i		
PARAMETER	SYMBOL	RATINGS	UNIT
Junction to Ambient	θ <sub>JA</sub>	75	°C/W
Junction to Case	θ <sub>JC</sub>	30	°C/W



## ■ ELECTRICAL CHARACTERISTICS (T<sub>A</sub>=25°C, unless otherwise specified)

		-		-		1	<b></b>	
PARAMETER		SYMBOL	TEST CONDITIONS	MIN	TYP	MAX	UNIT	
STATIC PARAMETERS			1	-				
Drain-Source Breakdown Voltage		BV <sub>DSS</sub>	I <sub>D</sub> =-250μA, V <sub>GS</sub> =0V	-60			V	
Zero Gate Voltage Drain Current		I <sub>DSS</sub>	V <sub>DS</sub> =-48V, V <sub>GS</sub> =0V			-1	μA	
			V <sub>DS</sub> =-48V, V <sub>GS</sub> =0V, T <sub>J</sub> =55°C			-5	μA	
Gate-Source Leakage Current	Forward		V <sub>GS</sub> =+20V, V <sub>DS</sub> =0V			+100	nA	
	Reverse	I <sub>GSS</sub>	V <sub>GS</sub> =-20V, V <sub>DS</sub> =0V			-100	nA	
ON CHARACTERISTICS								
Gate Threshold Voltage		V <sub>GS(TH)</sub>	V <sub>DS</sub> =V <sub>GS</sub> , I <sub>D</sub> =-250µA	-1	-2	-3	V	
On State Drain Current		I <sub>D(ON)</sub>	V <sub>GS</sub> =-10V, V <sub>DS</sub> =-5V	-40			Α	
		_	V <sub>GS</sub> =-10V, I <sub>D</sub> =-6.2A		43	48	mΩ	
Static Drain-Source On-State R	esistance	R <sub>DS(ON)</sub>	V <sub>GS</sub> =-4.5V, I <sub>D</sub> =-5A		58	63	mΩ	
Forward Transconductance		<b>g</b> fs	V <sub>DS</sub> =-5V, I <sub>D</sub> =-6.2A		18		S	
DYNAMIC PARAMETERS								
Input Capacitance	nput Capacitance				2417	2900	рF	
Output Capacitance Reverse Transfer Capacitance		C <sub>oss</sub>	V <sub>GS</sub> =0V, V <sub>DS</sub> =-30V, f=1.0MHz		179		pF	
		C <sub>RSS</sub>			120		pF	
Gate Resistance		R <sub>G</sub>	V <sub>GS</sub> =0V, V <sub>DS</sub> =0V, f=1MHz		1.9	2.3	Ω	
SWITCHING PARAMETERS								
Total Gate Charge		Q <sub>G</sub>	V <sub>GS</sub> =-4.5V, V <sub>DS</sub> =-30V, I <sub>D</sub> =-6.2A		22.7		nC	
Total Gate Charge		Q <sub>G</sub>			46.5	55	nC	
Gate to Source Charge		Q <sub>GS</sub>	V <sub>GS</sub> =-10V, V <sub>DS</sub> =-30V, I <sub>D</sub> =-6.2A		9.1		nC	
Gate to Drain Charge		Q <sub>GD</sub>	7		9.2		nC	
Turn-ON Delay Time		t <sub>D(ON)</sub>			9.8		ns	
Rise Time		t <sub>R</sub>	V <sub>GS</sub> =-10V, V <sub>DS</sub> =-30V, R <sub>L</sub> =4.7Ω,		6.1		ns	
Turn-OFF Delay Time	Turn-OFF Delay Time Fall-Time		R <sub>GEN</sub> =3Ω		44		ns	
· · · · ·			7		12.7		ns	
SOURCE- DRAIN DIODE RATI	INGS AND	CHARACTE	RISTICS					
Maximum Body-Diode Continuous		Is				4.0	•	
Current	-					-4.2	A	
Diode Forward Voltage		V <sub>SD</sub>	I <sub>S</sub> =-1A,V <sub>GS</sub> =0V		-0.74	-1	V	
Body Diode Reverse Recovery	Time	t <sub>rr</sub>			34	42	ns	
Body Diode Reverse Recovery	Charge	Q <sub>rr</sub>	l <sub>F</sub> =-6.2A, dl/dt=100A/μS		47		nC	
Note: 1. The value of $A_{-}$ is measured with the device mounted on $1i\sigma^{2}EP$ 4 heard with $2\sigma_{7}$ . Connect in a still air								

Notes: 1. The value of θ<sub>JA</sub> is measured with the device mounted on 1in<sup>2</sup>FR-4 board with 2oz. Copper, in a still air environment with T<sub>A</sub>=25°C.The value in any a given application depends on the user's specific board design. The current rating is based on the t ≤10s thermal resistance rating.

2. Repetitive rating, pulse width limited by junction temperature.

3. The  $\theta_{JA}$  is the sum of the thermal impedence from junction to lead  $\theta_{JL}$  and lead to ambient.





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